



**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re Application of:**

Salman Akram

**Serial No.:** 09/829,161

**Filed:** April 9, 2001

**For:** METALLIZATION STRUCTURES  
FOR SEMICONDUCTOR DEVICE  
INTERCONNECTS, METHODS FOR  
MAKING SAME, AND  
SEMICONDUCTOR DEVICES  
INCLUDING SAME

**Confirmation No.:** 8260

**Examiner:** H. Nguyen

**Group Art Unit:** 2812

**Attorney Docket No.:** 2269-3442.1US  
(96-0428.01/US)

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

September 11, 2003  
Date

Signature

Leah J. Barrow  
Name (Type/Print)

**SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

In compliance with the duty to disclose information material to patentability pursuant to 37 C.F.R. § 1.56, it is respectfully requested that this Supplemental Information Disclosure Statement be entered and the documents listed on attached Form PTO/SB/08 be considered by the Examiner and made of record. Copies of the listed documents are enclosed pursuant to 37 C.F.R. § 1.98(a). The listed documents were cited by the Office in co-pending application Serial No. 10/112,928, filed on March 29, 2002, and directed to a related invention.

In accordance with 37 C.F.R. § 1.97(g) and (h), filing of this Supplemental Information Disclosure Statement is not to be construed as a representation that a search has been made or an admission that the information cited herein is, or is considered to be, material to patentability as defined in 37 C.F.R. § 1.56(b). Further, no representation is made by Applicant herein that no other possible material information as defined in 37 C.F.R. § 1.56 (b) exists.

U.S. Patent Documents

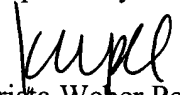
<u>U.S. Patent No.</u>	<u>Publication Date</u>	<u>Patentee</u>
US - 5,770,519	06/23/1998	Klein et al.
US - 2001/0044202 A1	11/22/2001	Huang et al.

Applicant offers to supply any explanation or discussion of the documents which the Examiner feels is necessary or desirable and which is requested.

This Supplemental Information Disclosure Statement is filed after the mailing date of the first Office Action on the merits.

I hereby certify that no item of information contained in the Supplemental Information Disclosure Statement was first cited in any communication from a foreign patent office in a counterpart foreign application or, to the knowledge of the undersigned after making reasonable inquiry, was known to any individual designated in 37 C.F.R. § 1.56(c) more than three months prior to the filing of the statement, and therefore no fee is due.

Respectfully submitted,

  
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Date: September 11, 2003

KWP/ps:ljb

Enclosures: Form PTO/SB/08 & copy of documents cited

Document in ProLaw

